

ON Semiconductor				10/15/2019
Base Part		FDMC86570L	HF	
Orderable Part		FDMC86570L	Total weight (mg)	70.648
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Clip	8.097	Zinc (Zn)	7440-66-6	0.13585278
		Iron (Fe)	7439-89-6	2.39594912
		Copper (Cu)	7440-50-8	97.4681981
Die	0.99	Silicon (Si)	7440-21-3	100
Die Attach Solder	1.989	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	20.211	Zinc (Zn)	7440-66-6	0.12864282
		Iron (Fe)	7439-89-6	2.39968334
		Copper (Cu)	7440-50-8	97.47167384
Mold Compound-Black	14.236	Ortho Cresol Novolac Resin	29690-82-2	5.00140489
		Carbon Black (C)	1333-86-4	0.9974712
		Fused Silica (SiO2)	60676-86-0	88.99971902
		Phenolic Resin (Novolac)	9003-35-4	5.00140489
Plating	25.1	Tin (Sn)	7440-31-5	100
Wire Bond - Au	0.025	Gold (Au)	7440-57-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				